# Easy to use mid-size vertical type push switch





# Typical Specifications

Items	Specifications		
Rating (max.)/(min.) (Resistive load)	0.1A 30V DC / 50 µA 3V DC		
Contact resistance (Initial performance)	100mΩ max.		
Operating force	2±1N		
Operating life with load	10,000 cycles (0.1A 30V DC)		

## Product Line

Changeover	Travel	Total travel	I Poles I Uneration I I ocati		oles Operation	Location lug-	Minimum order unit (pcs.)		Product No.	
timing (n	(mm)	m) (mm)	method	1 0.00	oporación.	type	20001.011.108	Japan	Export	1100001110.
Non shorting	2.2	2.2 3	PC board	2	Latching	Straight	With	1,200	6,000	SPPH410100
					Momentary Str					SPPH410200
					Latching		Without			SPPH420100
					Lo	Latering	Snap-in	With		
					Momentary	oriap-III	VVILII			SPPH430200

## Packing Specifications

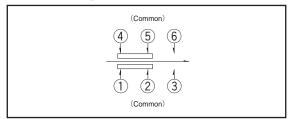
## Bulk

Number of pa	ckages (pcs.)	Export package measurements		
1 case / Japan 1 case / export packing		(mm)		
1,200	6,000	400×270×290		

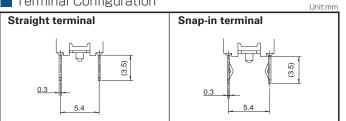
Dimensions Unit:mm PC board mounting hole dimensions (Viewed from the direction A) Style With boss (0.2) For location lug 6-ø0.9 hole Terminal No. 3 Thickness of PC board t=1.6mm Terminal No.② Location lug Terminal No.1

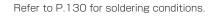
Note Dimensions drawing is for type with location lugs.

# ■ Circuit Diagram (Viewed from Direction A)



# ■ Terminal Configuration







Series			Vertical							
Conce			SPEH	SPEJ	SPPH4	SPPH1				
Photo			•							
W		W	6	7	6.5	10				
Dimensio (mm)	ns	D	6	7	8.5	10				
		Н	5	5.95	8.	5				
Tra	vel (mm)		_	_	2.2	1.5				
Total ·	travel (m	m)	1.6	1.7	3	2.5				
Numb	er of pol	es	1		2					
	erating ature rar	nge	-40°C to +90°C	-40℃ to +85℃	−10°C to	) +60℃				
Autor	notive us	se	•	•	_	•				
Lit	Life cycle		<b>1</b> 3	<b>*</b> 3	★3	<b>₹</b> 3				
Rati (Resi	Rating (max.) (Resistive load) 50mA 16V DC 0		0.2A 14V DC	0.1A 30V DC						
	ng (min.) stive loa		10μA 1V DC	_	50μA 3V DC					
Durability	Operating life without load		100,000 cycles $400$ max.	10,000cycles 150mΩ max.	10,000cycles 100mΩ max.	10,000cycles 40mΩ max.				
Durability	Operating life with load (at max. rated load)		100,000 cycles $400$ max.	10,000cycles 150mΩ max.	10,000cycles 100mΩ max.	10,000cycles 40mΩ max.				
	Initial contact resistance		200mΩ max.	150mΩ max.	100mΩ max.	20mΩ max.				
Electrical performance			100MΩ min. 100V DC		100MΩ min. 500V DC					
	Voltag	e proof	250V AC for 1minute	500V AC for 1minute						
		ninal ngth	_	_	5N for	lminute				
Mechanical performance	Actuato	Operating direction	50N	49N	30N	50N				
	strength		_	_	10N	_				
	Cold		-40℃ 1000h	-40°C 500h -20°C 96h		96h				
Environmental performance			90℃ 1000h	85°C 500h	85°C 500h 85°C 96h					
	Damp	) heat	60℃, 90 to 95%RH 1000h	60°C. 90 to 95%RH 500h	40°C, 90 to 9	95%RH 96h				
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# Note

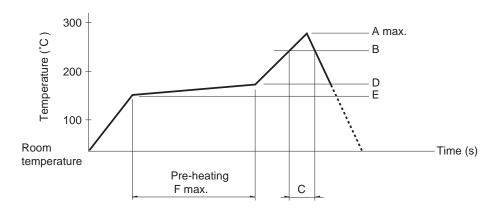
Indicates applicability to all products in the series.

# ■ Example of Reflow Soldering Condition

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple  $\phi$  0.1 to 0.2 CA (K) or CC (T) at soldering portion (copper foil surface). A heat resisting tape should be used for fixed measurement.

Push Switches / Soldering Conditions

3. Temperature profile



Series (Reflow type)	A (°C) 3s max.	B (℃)	C (s)	D (℃)	E (℃)	F (s)
SPEJ						
SPEF	260	230	40	180	150	120
SPEH						

#### Notes

- 1. The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc.

  The above-stated conditions shall also apply to switch surface temperatures.
- 2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

## Reference for Hand Soldering

Series	Soldering temperature	Soldering time
SPPJ3, SPPJ2, SPUN, SPUJ, SPPH4, SPPH1	350±10°C	3+1/0s
SPED2, SPED4	350±10℃	3±0.5s
SPEJ	350±10°C	4s max.
SPEF	350±5℃	3s max.
SPEH	350℃ max.	3s max.

## Reference for Dip Soldering

(For PC board terminal types)

Series	Ite	ms	Dip soldering		
Jelles	Preheating temperature	Preheating time	Soldering temperature	Duration of immersion	
SPPJ3	100℃ max.	60s max.	260±5℃	5±1s	
SPUN	100℃ max.	60s max.	260±5℃	10±1s	
SPUJ, SPPH4	_		260±5℃	5±1s	
SPPJ2, SPPH1, SPED2, SPED4, SPEF	_		260±5℃	10±1s	